

Semiconductor Optical Amplifier

RZSOA-1550-A-BS-FA-14

Features:

14-pin butterfly package (Shunt Clips - required to protect the butterfly package pins)

Built-in thermistor and TEC

Single mode input /output

Operating Temperature -20~ +70°C

Low chip-to-fiber coupling loss

Single-mode/PM fiber pigtail

Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Condition
Operating Case Temperature	T_c	-20	70	°C	--
Storage Temperature	T_{stg}	-40	85	°C	--
Laser Bias Current	I		100	mA	
Thermoelectric cooler voltage	V_{TEC}		2.6	V	
Thermoelectric cooler current	I_{TEC}		1.5	A	-20 °C < T_c < +70 °C
Lead solder Temperature	--		260	°C	--
Lead Soldering Time	--		10	s	--

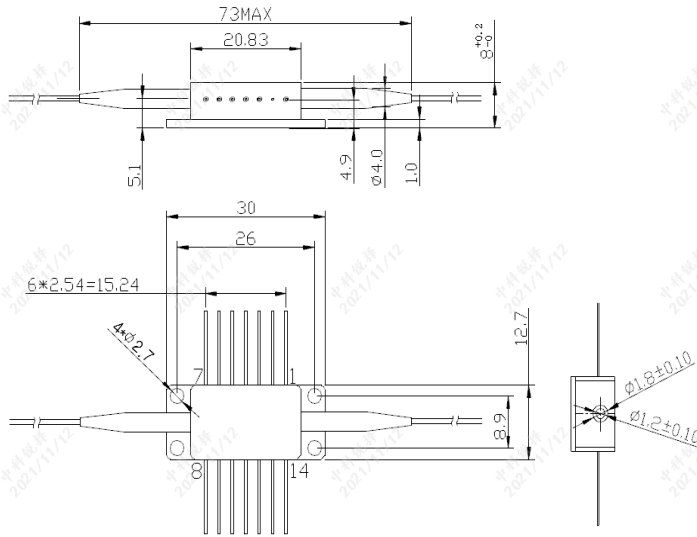
Optical/Electrical Characteristics (T=25°C, unless otherwise stated)

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions
Fiber-to-Fiber Gain	dB	--	20	--	dB	
Output Power	mW	--	2.0	--	mW	T=25 °C
Output Power	mW	--	1.6	--	mW	T=25 °C
Rise Time	ns	--	0.5	--	ns	
Forward Voltage	V_F	--	1.1	2.0	V	
Center Wavelength	λ_c	--	1310 1550	--	nm	CW, T=25 °C
Wavelength Band	nm	1290 1523	--	1330 1568	nm	
Back reflection	dB	--	<-47	--	dB	
Fibre Reflection	%	--	0.1	--	nm	
Spectral Width (FWHM)	nm	30	--	--	nm	
Thermistor Resistance	R_T	9.5	10.0	10.5	K Ω	T=25 °C
Thermistor B-Value		--	3950	--	K	25°C/85°C
Tracking Error	TE	-1.0	--	+1.0	dB	TE=10log(Po(Tc)/Po(25°C))

Dimensions and Pin Description

Dimensions are in millimeters. All dimensions are ± 0.1 mm unless otherwise specified.

Type: 00



Pin	Description
1	TEC(+)
2	Thermistor
3	N/C
4	N/C
5	Thermistor
6	N/C
7	N/C
8	N/C
9	N/C
10	SOA Anode (+)
11	SOA Cathode (-)
12	N/C
13	Case GND
14	TEC(-)

Order information

RZSOA-1550-A-BS-FA-14

RZLD	wavelength	Output Power	encapsulation & Fiber selection	Connector	PIN
RZLD=LD	...nm	...mW	BP=BTF PM Fiber	00=NO	14
RZSLD=SLED	1064	5	BS=BTF SM Fiber	FA=FC/APC	10
RZNLD=Narrow line width	1310	50	BM=BTF MM Fiber	FU=FC/UPC	8
RZPLD= Pulsed laser	1550	200	DP=DIP PM Fiber	SA=SC/APC	
RZSOA=SOA	...	400	
...		...			

Note: The laser module are ESD-sensitive devices. Please ensure that proper ESD handling procedures are followed.